SPECIFICATIONS

Customer						
Product Name		Wire Wound Molded SMD Power Inductors				
Sunlord Part N	umber	MWSA Series				
Customer Part	Number					
[⊠New Release	d,	ed]		SF	PEC No.: N	//WSA0617
This SPEC is total 2		ding speci	fications an	d appendix	.]	
	Approved I	By Che	cked By	Issued	I By	
Shenzheddress: Sunlord Indu	ustrial Park, Da	fuyuan Ind		, Guanlan,	Shenzhen, C	
ddress: Sunlord Indu el: 0086-755-298326 For Customer app	ustrial Park, Da 660 Fax roval Only I	fuyuan Ind : 0086-755	ustrial Zone -82269029	, Guanlan, E-Mail	Shenzhen, C sunlord@si	China 5181
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【Version change history】

Rev.	Effective Date	Changed Contents	Change Reasons	Approved By
01	1	New release	1	Hai Guo

Scope

This specification applies to MWSA series of wire wound molded SMD power Inductors

Product Description and Identification (Part Number)

Description

Wire Wound Molded SMD Type Power Inductor, MWSAXXXX, XX $\mu H\pm X\%$ @XXX KHz/XXXV, XXXm Ω , XXXm A.

2) Product Identification (Part Number)

MWSA	XXXX	-XXX		<u>T</u>
1	2	3	4	(5)

1)	Туре
MWSA	Wire wound molded SMD power
IVIVVSA	Inductors

2	External Dimensions (mm)
	0412~1205

③ Nominal Inductance		
Example	Nominal Value	
1R0	1.0µH	
100	10μH	
101	100µH	

④ Inductance Tolerance		
	М	±20%

⑤ Packing		
Т	Tape Carrier Package	

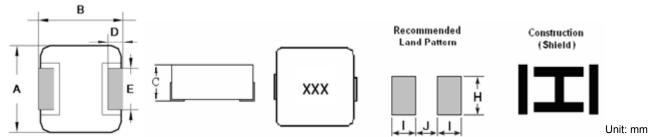
Electrical Characteristics

Please refer to Appendix A.

- Operating temperature range (Including self-heating): -55°C~+125°C.
- Storage temperature and humidity range (product with tapping): -10 ℃~+40 ℃, RH 70% Max.

Shape and Dimensions

Dimensions and recommended PCB pattern for reflow soldering: See Fig.4-1 and Table 4-1. 1)



					14 214 21			
Series	А	В	С	D	Е	l typ.	J typ.	H typ.
MWSA0412	4.2±0.25	4.4±0.35	1.0±0.2	0.8±0.3	2.0±0.3	1.5.	2.2	2.5
MWSA0402	4.2±0.25	4.4±0.35	1.8±0.2	0.8±0.3	2.0±0.3	1.5.	2.2	2.5
MWSA0518	5.2±0.2	5.4±0.3	1.6±0.2	1.20±0.2	2.2±0.3	1.9	2.2	2.5
MWSA0503	5.2±0.2	5.4±0.3	2.8±0.2	1.20±0.2	2.2±0.3	1.9.	2.2	2.5
MWSA0618	6.6±0.2	7.0±0.3	1.6±0.2	1.60±0.3	3.0±0.3	2.35	3.7	3.5
MWSA0624	6.6±0.2	7.0±0.3	2.2±0.2	1.60±0.3	3.0±0.3	2.35	3.7	3.5
MWSA0603	6.6±0.2	7.0±0.3	2.8±0.2	1.60±0.3	3.0±0.3	2.35	3.7	3.5
MWSA1004	10.0±0.3	11.5Max	3.8±0.2	2.0±0.5	3.0±0.5	4.1	5.4	4.1
MWSA1205	12.6±0.3	13.45±0.35	4.8±0.2	2.0±0.5	See Remarks	3.25	8.0	5.0

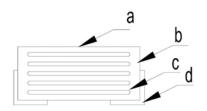
Remarks:

	Dimer	nsions
Code	R36/R50/R68	3R3/100/150
	1R0/1R5/2R2	220/330/470
E	3.85±0.5	5.0±0.5

Structure and Components: See Table 4-2

Table 4-2]

Symbol	Components	Material
а	MARKING	Ink(black)
b	CORE	Alloy Sponge Powder
С	WIRE	Polyurethane copper wire
d	Terminal	Copper plated with Sn



Test and Measurement Procedures

5.1 Test Conditions

5.1.1 Unless otherwise specified, the standard atmospheric conditions for measurement/test as:

a. Ambient Temperature: 20±15℃ b. Relative Humidity: 65±20% c. Air Pressure: 86 KPa to 106 KPa

5.1.2 If any doubt on the results, measurements/tests should be made within the following limits:

a. Ambient Temperature: 20±2℃ Relative Humidity: 65±5% b. c. Air Pressure: 86KPa to 106 KPa

5.2 Visual Examination

a. Inspection Equipment: 10 X magnifier

5.3 Electrical Test

5.3.1 DC Resistance (DCR)

a. Refer to Appendix A.

Test equipment (Analyzer): HIOKI3540 or equivalent.

5.3.2 Inductance (L)

a. Refer to Appendix A.

b. Test equipment: Wayne kerr3260+3265B or equivalent.

5.3.3 Rated Current

a. Refer to Appendix A.

b. Test equipment: Wayne kerr3260+3265B, Agilent E3633A, R2M-2H3 or equivalent.

Definition of Rated Current (Ir): With the condition of the DC current pass, the inductance decrease by 30% of the standard value, compare to the temperature rise by 40°C, the smaller is Rated Current.(reference environment temperature:20°C)

5.4 Reliability Test

Mechanical Reliability			
Item	Specification and Requirement	Test Method	
	The surface of terminal immersed shall be	Solder heat proof:	
Solderability	minimum of 95% covered with a new coating of	1. Preheating: 160 ± 10 $^{\circ}\mathrm{C}$	
	solder	2. Retention time: 245 ± 5 $^{\circ}$ C for 2 ± 0.5 seconds	
		Vibration frequency:	
		(10 Hz to 55 Hz to 10Hz) in 60 seconds as a period	
Vibration	Inductance change: Within ± 10% Without	2. Vibration time:	
Vibration	mechanical damage such as break	Period cycled for 2 hours in each of 3 mutual perpendicular	
		directions.	
		3. Amplitude: 1.5 mm max.	
		1. Peak value: 100 G	
Shock	Inductance change: Within ± 10% Without	2. Duration of pulse: 11ms	
SHOCK	mechanical damage such as break	3. 3 times in each positive and negative direction of 3 mutual	
		perpendicular directions	
Endurance Reliabili	ty		
Item	Specification and Requirement	Test Method	
	Industrance change: Within ± 100/ Without distinct	Repeat 100 cycles as follow:	
Thermal Shock	Inductance change: Within ± 10% Without distinct	(-55 ± 2 °C; 30 ± 3 min)	
	damage in appearance	→(Room temp., 5 min)	

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- Sulliold Ca	ategories, general confidential Specifications for	AAII	e wound moided SMD Fower inductors Fage 5 of 26
			\rightarrow (+125 ± 2 °C, 30 ± 3 min)
			\rightarrow (Room temp., 5 min)
		2.	Recovery: 48 + 4 / -0 hours of recovery under the standard
			condition after the test.
High Tages and we	Laduration of the control of the con	1.	Environment condition: 85 ± 2 °C
High Temperature	Inductance change: Within ± 10% Without distinct		Applied Current: Rated current
Resistance	damage in appearance	2.	Duration: 1000 + 4 / -0 hours
		1.	Environment condition: 60 ± 2 °C
Humidity	Inductance change: Within ±10% Without distinct		Humidity: 90–95%
Resistance	damage in appearance		Applied Current: Rated current
		2.	Duration: 1000 + 4 / -0 hours
Low Temperature	Inductance change: Within ± 10% Without distinct		Store temperature:
Store	damage in appearance		-55 \pm 2 $^{\circ}$ C,1000 + 4 / -0 hours
High Temperature	Inductance change: Within ± 10% Without distinct		Store temperature:
Store	damage in appearance		+125 ± 2 °C,1000 + 4 / -0 hours

6. Packaging, Storage and Transportation

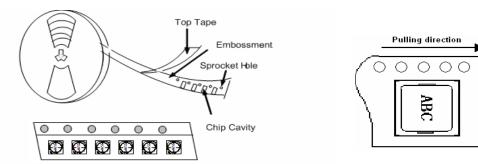
6.1 Tape Carrier Packaging:

Packaging code: T

- (1) Tape carrier packaging are specified in attached figure Fig.6.1-1~2
- (2) Tape carrier packaging quantity:

Туре	Standard Quantity (pcs/reel)	Туре	Standard Quantity (pcs/reel)
MWSA0412	3000	MWSA0624	1500
MWSA0402	3000	MWSA0603	1500
MWSA0518	2000	MWSA1004	500
MWSA0503	2000	MWSA1205	500
MWSA0618	1500		

a. Taping Drawings (Unit: mm)



Remark: The sprocket holes are to the right as the tape is pulled toward the user.

Fig.6.1-1

b.Reel and Taping Dimensions (Unit: mm)

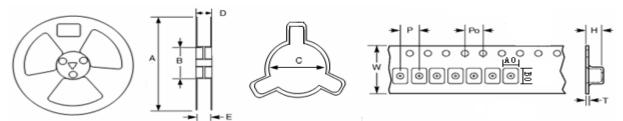
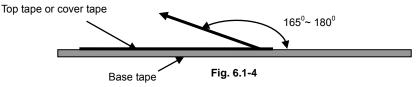


Fig.6.1-2

Time		Reel dimensions (mm)			Tape dimensions (mm)							
Туре	Α	В	С	D	E	W	Р	P0	Н	Т	A0	В0
MWSA0412	330±2.0	100±1.0	13±1.0	16.5±0.9	12.5±0.5	12±0.3	8±0.1	4±0.1	1.4±0.15	0.35 ± 0.05	4.5±0.1	4.8±0.1
MWSA0402	330±2.0	100±1.0	13±1.0	16.5±0.6	12.5±0.2	12±0.3	8±0.1	4±0.1	2.5±0.15	0.35 ± 0.05	4.5±0.1	4.8±0.1
MWSA0518	330±2.0	100±1.0	13±1.0	16.5±0.6	12.5±0.2	12±0.3	8±0.1	4±0.1	2.3±0.15	0.35 ± 0.05	5.7±0.1	5.9±0.1
MWSA0503	330±2.0	100±1.0	13±1.0	16.5±0.6	12.5±0.2	12±0.3	8±0.1	4±0.1	3.3±0.15	0.35 ± 0.05	5.7±0.1	5.9±0.1
MWSA0618	330±2.0	100±1.0	13±1.0	20.5±0.6	16.5±0.2	16±0.3	12±0.1	4±0.1	2.3±0.15	0.31±0.05	7.2±0.1	7.5±0.1
MWSA0624	330±2.0	100±1.0	13±1.0	20.5±0.6	16.5±0.2	16±0.3	12±0.1	4±0.1	3.6±0.15	0.31±0.05	7.2±0.1	7.5±0.1
MWSA0603	330±2.0	100±1.0	13±1.0	20.5±0.6	16.5±0.2	16±0.3	12±0.1	4±0.1	3.6±0.15	0.31±0.05	7.2±0.1	7.5±0.1
MWSA1004	330±2.0	100±1.0	13±1.0	28.5±0.6	24.5±0.2	24±0.3	16±0.1	4±0.1	4.5±0.1	0.35±0.025	10.7±0.1	12.0±0.1
MWSA1205	330±2.0	100±1.0	13±1.0	28.5±0.6	24.5±0.2	24±0.3	16±0.1	4±0.1	5.4±0.15	0.5±0.05	13.4±0.1	14.4±0.1

- c.Inner boxes high for 30mm or 35mm on 12-16mm Carrier tape, Inner boxes high for 35mm or 40mm on 24mm Carrier tape, A reel of a box .
- d.Peeling off force: 10gf to 130gf in the direction show below.



6.2 Storage

- (1) The solderability of the external electrodes may deteriorate if packages are stored in high humidity. Besides, to ensure packing material's good state, packages must be stored at -10 $^{\circ}$ C to 40 $^{\circ}$ C and 70% RH Max.
- (2) The solderability of the external electrodes may deteriorate if packages are exposed to dust of harmful gas (e.g. HCl, sulfurous gas of H₂S).
- (3) Packaging materials may deform if packages are exposed directly to sunlight.
- (4) Minimum packages, such as polyvinyl heat-seal packages shall not be opened until they are used. If opened, use the reels as soon as possible.
- (5) Solderability shall be guaranteed for a period of time from the date of delivery on condition that they are stored at the specified environment. For those parts, which passed more than the time shall be checked solderability before using.
- (6) For magnetic products, keep clear of anything that may generate magnetic fields to avoid change of products performance.
- (7) To avoid any damage to products, do not load mechanic force on products or place heavy goods on products, and exclude strong vibration or drop.
- (8)In case of storage over 12 months, solderability shall be checked before actual usage.

7. Warning and Attentions

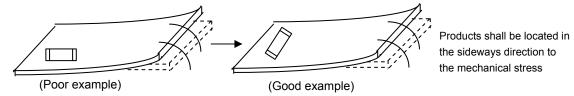
- 7.1 Precautions on Use
 - (1) Always wear static control bands to protect against ESD.
 - (2) Any devices used with the products (soldering irons, measuring instruments) should be properly grounded.
 - (3) Keep bare hands and metal conductors (i.e., metal desk) away from electrodes or conductive areas that lead to electrodes.
 - (4) Preheat when soldering.
 - (5) Don't apply current in excess of the rated current value. It may reduce the impedance or inductance, or cause damage to components due to over-current.
 - (6) For magnetic products, keep clear of anything that may generate magnetic fields such as speakers and coils. Use non-magnetic tweezers when handing the chips.
 - (7) When soldering, the electrical characteristics may be varied due to hot energy and mechanical stress.
 - (8) When coating products with resin, the relatively high resin curing stress may change the electrical characteristics. For exterior coating, select resin carefully so that electrical and mechanical performance of the product is not affected. Before using, please evaluate reliability with the product mounted in your application set.
 - (9) When mount chips with adhesive in preliminary assembly, do appropriate check before the soldering stage, i.e., the size of land pattern, type of adhesive, amount applied, hardening of the adhesive on proper usage and amounts of adhesive to use.
 - (10) Mounting density: Add special attention to radiating heat of products when mounting other components nearby. The excessive heat by other products may cause deterioration at joint of this product with substrate.
 - (11) Since some products are constructed like an open magnetic circuit, narrow spacing between components may cause magnetic coupling.
 - (12) Please do not give the product any excessive mechanical shocks in transportation.
 - (13) Please do not touch wires by sharp terminals such as tweezers to avoid causing any damage to wires.
 - (14) Please do not add any shock and power to the soldered product to avoid causing any damage to chip body.

(15) Please do not touch the electrodes by naked hand as the solderability of the external electrodes may deteriorate by grease or oil on the skin.

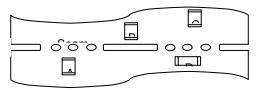
7.2 PCB Bending Design

The following shall be considered when designing and laying out PCB's.

(1) PCB shall be designed so that products are not subjected to the mechanical stress from board warp or deflection.



(2) Products location on PCB separation.



Product shall be located carefully because they may be subjected to the mechanical stress in order of A>C=B>D.

- (3) When splitting the PCB board, or insert (remove) connector, or fasten thread after mounting components, care is required so as not to give any stress of deflection or twisting to the board. Because mechanical force may cause deterioration of the bonding strength of electrode and solder, even crack of product body. Board separation should not be done manually, but by using appropriate devices.
- 7.3 Recommended PCB Design for SMT Land-Patterns

When chips are mounted on a PCB, the amount of solder used (size of fillet) can directly affect chip performance. Therefore, the following items must be carefully considered in the design of solder land patterns:

- (1) The amount of solder applied can affect the ability of chips to withstand mechanical stresses which may lead to breaking or cracking. Therefore, when designing land-patterns it is necessary to consider the appropriate size and configuration of the solder pads which in turn determines the amount of solder necessary to form the fillets.
- (2) When more than one part is jointly soldered onto the same land or pad, the pad must be designed that each component's soldering point is separated by solder-resist.
 - Recommended land dimensions please refer to product specification.

8 **Recommended Soldering Technologies**

8.1Re-flowing Profile:

Preheat condition: 150 ~200 °C/60~120sec.

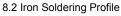
Allowed time above 217°C: 60~90sec. Δ

Δ Max temp: 260°C

△ Max time at max temp: 10sec. Λ Solder paste: Sn/3.0Ag/0.5Cu Allowed Reflow time: 2x max \wedge Please refer to Fig. 8.1

[Note: The reflow profile in the above table is only for qualification and is not meant to specify board assembly profiles. Actual board assembly profiles must be based on the customer's specific board design, solder paste and process,

and should not exceed the parameters as the Reflow profile shows.]



Iron soldering power: Max. 30W Δ

Δ Pre-heating: 150°C/60sec.

Soldering Tip temperature: 350°C Max. Λ

Soldering time: 3sec. Max. Λ Δ Solder paste: Sn/3.0Ag/0.5Cu △ Max.1 times for iron soldering Please refer to Fig. 8.2.

[Note: Take care not to apply the tip of the soldering iron to the terminal electrodes.]

8.3 Recommended Soldering Technologies Heat Gun Profile

△ Soldering tip temperature: 350°C Max.

△ Hot air time: <5sec (over 5sec may cause wiring inductor short)

When repairing or reworking the component near inductors, take over-heat protection for Inductors

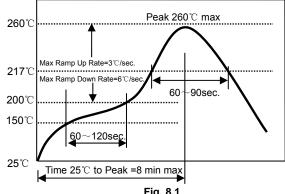


Fig. 8.1

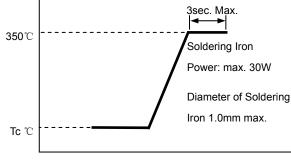


Fig. 8.2.

9. Solder Volume

Solder shall be used not to exceed as shown below. Exceeding solder volume may cause the failure of mechanical or electrical performance.



10. Supplier Information

a) Supplier:

Shenzhen Sunlord Electronics Co., Ltd.

b) Manufacturer:

Shenzhen Sunlord Electronics Co., Ltd.

c) Manufacturing Address:

Sunlord Industrial Park, Dafuyuan Industrial Zone, Guanlan, Shenzhen, China

Zip: 518110

Appendix A: Electrical Characteristics

MWSA0412 TYPE

Part Number	Inductance	L Test Condition	Max. DC Resistance	Typ. Saturation Current	Typ. Heat Rating Current
Units	μH	Hz, V	mΩ	Α	А
Symbol	L	-	DCR	Isat	Irms
MWSA0412-R15MT	0.15	100k, 1.0V	9.0	15.0	7.5
MWSA0412-R22MT	0.22	100k, 1.0V	11.0	11.0	7.0
MWSA0412-R33MT	0.33	100k, 1.0V	19	8.4	6.5
MWSA0412-R47MT	0.47	100k, 1.0V	21	6.8	6.0
MWSA0412-R68MT	0.68	100k, 1.0V	36	6.0	4.7
MWSA0412-1R0MT	1.0	100k, 1.0V	47	5.5	4.5
MWSA0412-1R5MT	1.5	100k, 1.0V	75	4.0	3.25
MWSA0412-2R2MT	2.2	100k, 1.0V	83.5	3.0	2.75
MWSA0412-4R7MT	4.7	100k, 1.0V	195	2.2	1.8

MWSA0402 TYPE

Part Number	Inductance	L Test Condition	Max. DC Resistance	Typ. Saturation Current	Typ. Heat Rating Current
Units	μH	Hz, V	mΩ	А	Α
Symbol	L	-	DCR	Isat	Irms
MWSA0402-R10MT	0.10	100k, 1.0V	4.0	22.0	13.0
MWSA0402-R22MT	0.22	100k, 1.0V	6.6	12.5	9.5
MWSA0402-R33MT	0.33	100k, 1.0V	11.0	12.0	10.0
MWSA0402-R47MT	0.47	100k, 1.0V	14	9.5	7.5
MWSA0402-R56MT	0.56	100k, 1.0V	16	9.0	7.0
MWSA0402-R68MT	0.68	100k, 1.0V	18	8.0	7.0
MWSA0402-1R0MT	1.0	100k, 1.0V	27	7.0	6.0
MWSA0402-1R2MT	1.2	100k, 1.0V	27	6.5	6.0
MWSA0402-1R5MT	1.5	100k, 1.0V	46	5.5	5.0
MWSA0402-2R2MT	2.2	100k, 1.0V	58	5.0	4.5
MWSA0402-3R3MT	3.3	100k, 1.0V	87	3.5	3.3
MWSA0402-4R7MT	4.7	100k, 1.0V	105	3.0	2.8
MWSA0402-6R8MT	6.8	100k, 1.0V	175	2.5	2.4
MWSA0402-100MT	10.0	100k, 1.0V	282	2.0	1.6
MWSA0402-220MT	22.0	100k, 1.0V	363	1.4	1.2

MWSA0518 TYPE

Part Number	Industance	L Toot Condition	Max. DC	Typ. Saturation	Typ. Heat Rating
Part Number	Inductance	L Test Condition	Resistance	Current	Current
Units	μH	Hz, V	mΩ	А	Α
Symbol	L	•	DCR	Isat	Irms
MWSA0518-R47MT	0.47	100k, 1.0V	9	12.0	10.5
MWSA0518-R56MT	0.56	100k, 1.0V	10	11	9.5
MWSA0518-1R0MT	1.0	100k, 1.0V	17	9.0	8.0
MWSA0518-1R5MT	1.5	100k, 1.0V	26	8	7.5

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MWSA0518-2R2MT	2.2	100k, 1.0V	35	6.0	5.0
MWSA0518-3R3MT	3.3	100k, 1.0V	58	4.8	4.5
MWSA0518-4R7MT	4.7	100k, 1.0V	85	4.0	3.5
MWSA0518-6R8MT	6.8	100k, 1.0V	120	3.4	2.8
MWSA0518-100MT	10.0	100k, 1.0V	155	2.5	2.5

MWSA0503 TYPE

Part Number	Inductance	L Test Condition	Max. DC Resistance	Typ. Saturation Current	Typ. Heat Rating Current
Units	μH	Hz, V	mΩ	А	Α
Symbol	L	-	DCR	Isat	Irms
MWSA0503-R10MT	0.1	100k, 1.0V	3.0	30	25
MWSA0503-R20MT	0.2	100k, 1.0V	3.9	20	14
MWSA0503-R33MT	0.33	100k, 1.0V	5.5	18	14
MWSA0503-R47MT	0.47	100k, 1.0V	8.5	15	11
MWSA0503-R68MT	0.68	100k, 1.0V	12.0	11.5	9.0
MWSA0503-1R0MT	1.0	100k, 1.0V	14	10	8.5
MWSA0503-1R2MT	1.2	100k, 1.0V	16	9.5	8.5
MWSA0503-1R5MT	1.5	100k, 1.0V	25	9	8.2
MWSA0503-2R2MT	2.2	100k, 1.0V	29	7.0	7.0
MWSA0503-3R3MT	3.3	100k, 1.0V	38	6.0	5.5
MWSA0503-4R7MT	4.7	100k, 1.0V	60	4.6	4.5
MWSA0503-6R8MT	6.8	100k, 1.0V	90	3.6	3.5
MWSA0503-100MT	10.0	100k, 1.0V	125	3.5	3.2

MWSA0618 TYPE

Part Number	Inductance	L Test Condition	Max. DC Resistance	Typ. Saturation Current	Typ. Heat Rating Current
Units	μH	Hz, V	mΩ	A	A
Symbol	L	-	DCR	Isat	Irms
MWSA0618-R10MT	0.10	100k, 1.0V	2.3	38	25
MWSA0618-R22MT	0.22	100k, 1.0V	3.5	24	22
MWSA0618-R47MT	0.47	100k, 1.0V	8.4	18.0	11.5
MWSA0618-R68MT	0.68	100k, 1.0V	12	16.5	9.5
MWSA0618-1R0MT	1.0	100k, 1.0V	16	12	8.5
MWSA0618-1R5MT	1.5	100k, 1.0V	26	9.2	8
MWSA0618-2R2MT	2.2	100k, 1.0V	35	8	7
MWSA0618-3R3MT	3.3	100k, 1.0V	50	6.0	4.5
MWSA0618-4R7MT	4.7	100k, 1.0V	62	5.0	4.0
MWSA0618-6R8MT	6.8	100k, 1.0V	110	4.5	3.0
MWSA0618-100MT	10	100k, 1.0V	155	4.0	2.3
MWSA0618-220MT	22	100k, 1.0V	350	2.3	1.8

MWSA0624 TYPE

Part Number	Inductance	L Test Condition	Max. DC Resistance	Typ. Saturation Current	Typ. Heat Rating Current
Units	μH	Hz, V	mΩ	А	А
Symbol	L	-	DCR	Isat	Irms
MWSA0624-R22MT	0.22	100k, 1.0V	3.0	30	21
MWSA0624-R33MT	0.33	100k, 1.0V	4.1	24.5	18
MWSA0624-R47MT	0.47	100k, 1.0V	5.1	20	15
MWSA0624-R56MT	0.56	100k, 1.0V	6.5	17	13
MWSA0624-R68MT	0.68	100k, 1.0V	7.0	16	12
MWSA0624-1R0MT	1.0	100k, 1.0V	13.5	15	9.0
MWSA0624-1R5MT	1.5	100k, 1.0V	20	13.5	8.2
MWSA0624-2R2MT	2.2	100k, 1.0V	28	10	7.0
MWSA0624-3R3MT	3.3	100k, 1.0V	39	8	5.5
MWSA0624-4R7MT	4.7	100k, 1.0V	50	6.5	5.0
MWSA0624-6R8MT	6.8	100k, 1.0V	70	6.0	4.0
MWSA0624-100MT	10.0	100k, 1.0V	101	4.0	3.1
MWSA0624-150MT	15.0	100k, 1.0V	160	3.3	2.5
MWSA0624-220MT	22.0	100k, 1.0V	230	2.5	2.0

MWSA0603 TYPE

Part Number	Inductance	L Test Condition	Max. DC Resistance	Typ. Saturation Current	Typ. Heat Rating Current
Units	μH	Hz, V	mΩ	А	Α
Symbol	L	-	DCR	Isat	Irms
MWSA0603-R22MT	0.22	100k, 1.0V	3.0	34	24
MWSA0603-R24MT	0.24	100k, 1.0V	3.1	26	23
MWSA0603-R33MT	0.33	100k, 1.0V	3.5	25	21
MWSA0603-R47MT	0.47	100k, 1.0V	4.1	19	18
MWSA0603-R56MT	0.56	100k, 1.0V	4.5	18	16.5
MWSA0603-R68MT	0.68	100k, 1.0V	5.3	17	16
MWSA0603-R82MT	0.82	100k, 1.0V	6.0	16	14
MWSA0603-1R0MT	1.0	100k, 1.0V	7.4	14	12
MWSA0603-1R5MT	1.5	100k, 1.0V	12.1	12	12
MWSA0603-2R2MT	2.2	100k, 1.0V	15	10	9.5
MWSA0603-3R3MT	3.3	100k, 1.0V	22	9.5	8.5
MWSA0603-4R7MT	4.7	100k, 1.0V	33	6.2	6
MWSA0603-6R8MT	6.8	100k, 1.0V	48	5.5	5
MWSA0603-8R2MT	8.2	100k, 1.0V	60	5.5	5
MWSA0603-100MT	10	100k, 1.0V	67	5.2	4.5
MWSA0603-150MT	15	100k, 1.0V	115	4.0	3.0
MWSA0603-220MT	22	100k, 1.0V	200	3.0	2.3
MWSA0603-330MT	33	100k, 1.0V	310	2.5	2.0

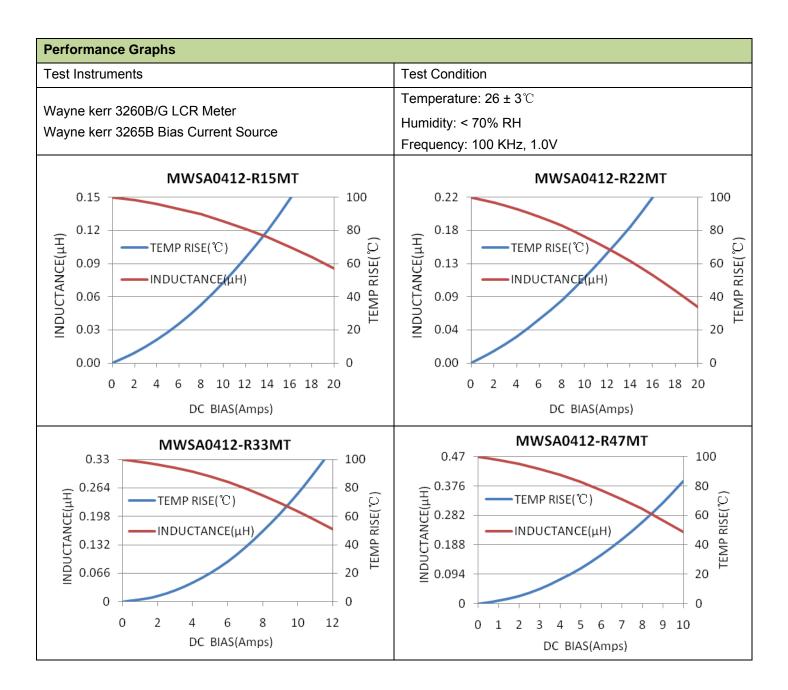
MWSA1004 TYPE

Part Number	Inductance	L Test Condition	Max. DC Resistance	Typ. Saturation Current	Typ. Heat Rating Current
Units	μH	Hz, V	mΩ	А	А
Symbol	L	-	DCR	Isat	Irms
MWSA1004-R15MT	0.15	100k, 1.0V	0.65	75	45
MWSA1004-R22MT	0.22	100k, 1.0V	1.0	60	35
MWSA1004-R30MT	0.30	100k, 1.0V	1.1	45	35
MWSA1004-R36MT	0.36	100k, 1.0V	1.2	45	30
MWSA1004-R47MT	0.47	100k, 1.0V	1.7	40	30
MWSA1004-R56MT	0.56	100k, 1.0V	1.8	33	25
MWSA1004-R68MT	0.68	100k, 1.0V	2.4	30	23
MWSA1004-R80MT	0.80	100k, 1.0V	2.7	29	23
MWSA1004-1R0MT	1.0	100k, 1.0V	3.3	28	19
MWSA1004-1R5MT	1.5	100k, 1.0V	4.2	24	16
MWSA1004-2R2MT	2.2	100k, 1.0V	7.0	16.5	12
MWSA1004-3R3MT	3.3	100k, 1.0V	11.8	16	11
MWSA1004-4R7MT	4.7	100k, 1.0V	20	13	9.0
MWSA1004-6R8MT	6.8	100k, 1.0V	25	12	8.5
MWSA1004-8R2MT	8.2	100k, 1.0V	27	9	8.0
MWSA1004-100MT	10	100k, 1.0V	30	8.5	7.8
MWSA1004-150MT	15	100k, 1.0V	45	7	6.5
MWSA1004-220MT	22	100k, 1.0V	66	5.5	5.0
MWSA1004-330MT	33	100k, 1.0V	92	4.8	4.4
MWSA1004-470MT	47	100k, 1.0V	145	3.5	3.3
MWSA1004-680MT	68	100k, 1.0V	195	3	2.5

MWSA1205 TYPE

Part Number	Inductance	L Test Condition	Max. DC Resistance	Typ. Saturation Current	Typ. Heat Rating Current
Units	μH	Hz, V	mΩ	А	А
Symbol	L	-	DCR	Isat	Irms
MWSA1205-R22MT	0.22	100k, 1.0V	0.7	75	50
MWSA1205-R36MT	0.36	100k, 1.0V	0.85	50	42
MWSA1205-R50MT	0.50	100k, 1.0V	1.15	48	38
MWSA1205-R68MT	0.68	100k, 1.0V	1.55	46	33
MWSA1205-R82MT	0.82	100k, 1.0V	1.67	39	30

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	MWSA1205-1R0MT	1.0	100k, 1.0V	2.2	35	26
	MWSA1205-1R5MT	1.5	100k, 1.0V	3.2	33	23
	MWSA1205-2R2MT	2.2	100k, 1.0V	5.0	24	15
	MWSA1205-3R3MT	3.3	100k, 1.0V	7	22	14
	MWSA1205-4R7MT	4.7	100k, 1.0V	9	20	13
	MWSA1205-6R8MT	6.8	100k, 1.0V	18	16	12
	MWSA1205-100MT	10	100k, 1.0V	22	12	9
	MWSA1205-150MT	15	100k, 1.0V	30	10	8
	MWSA1205-220MT	22	100k, 1.0V	58	6.5	4.5
	MWSA1205-330MT	33	100k, 1.0V	84	6.0	3.5
	MWSA1205-470MT	47	100k, 1.0V	130	5.0	3.0



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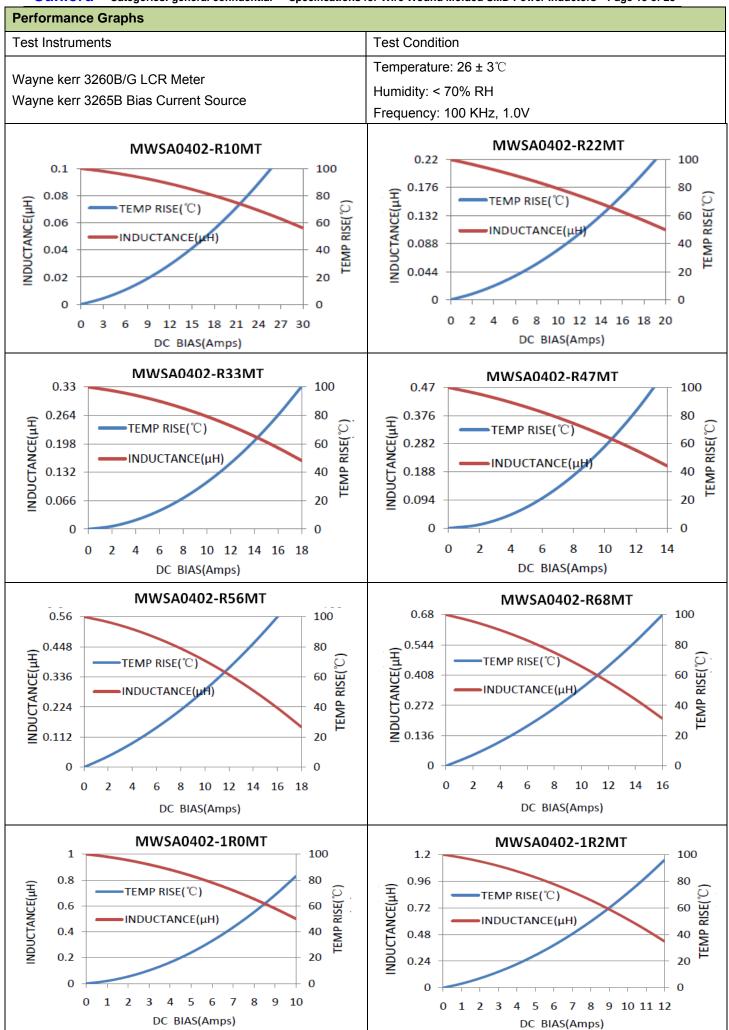
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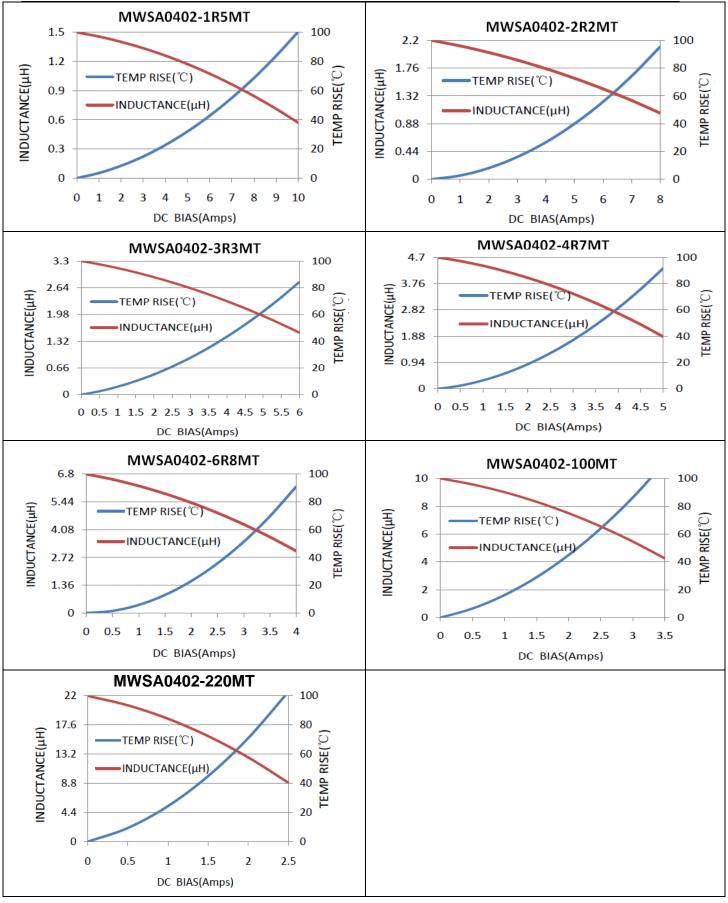
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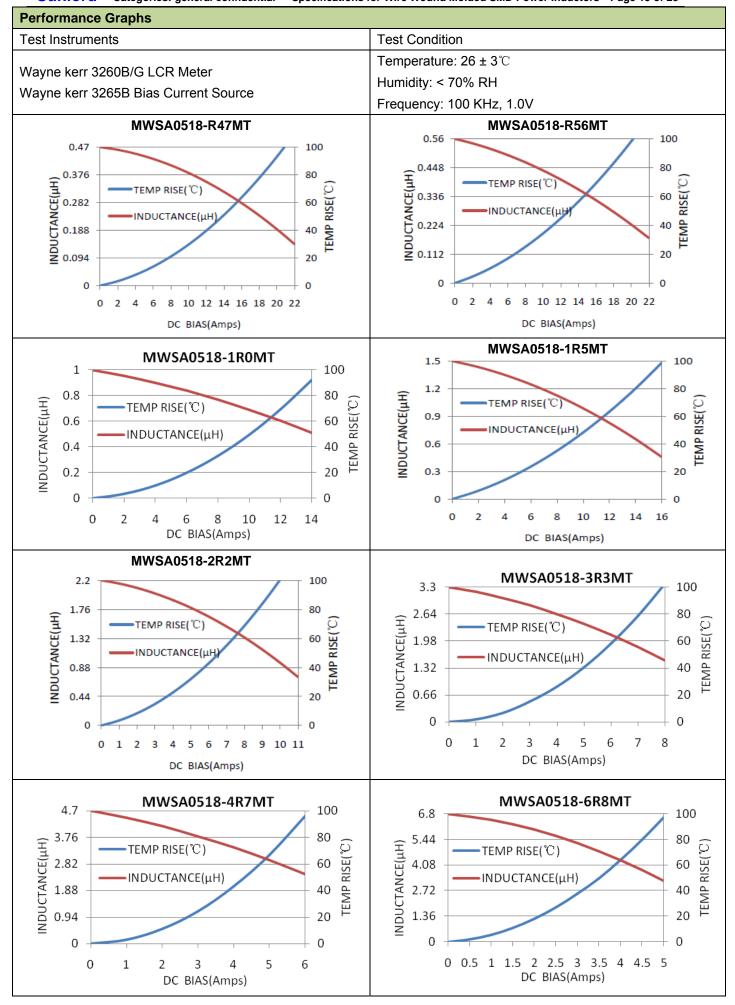
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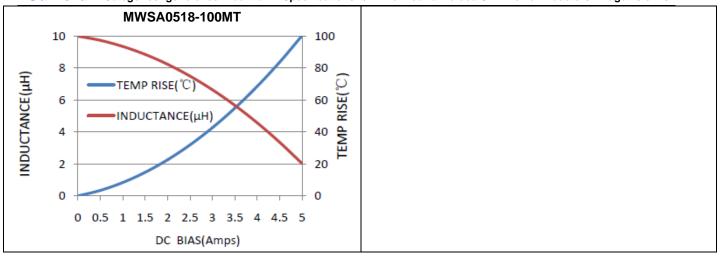
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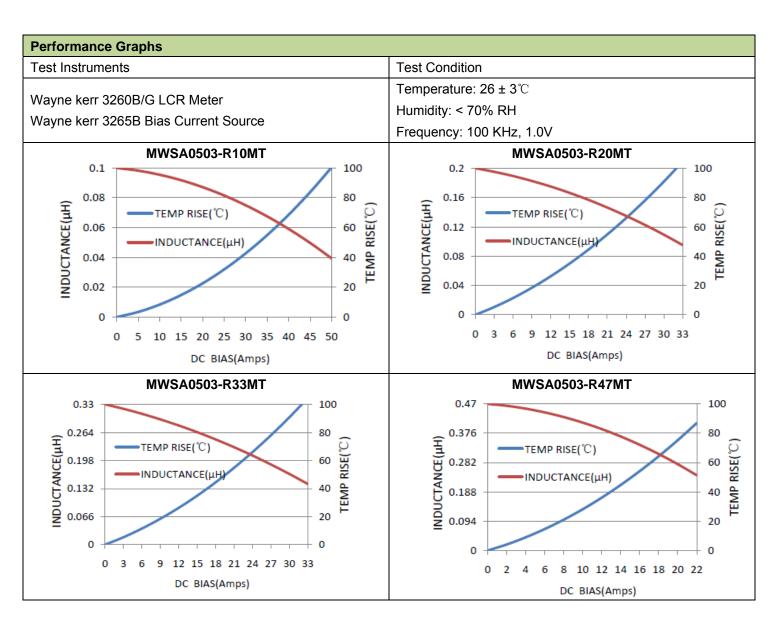






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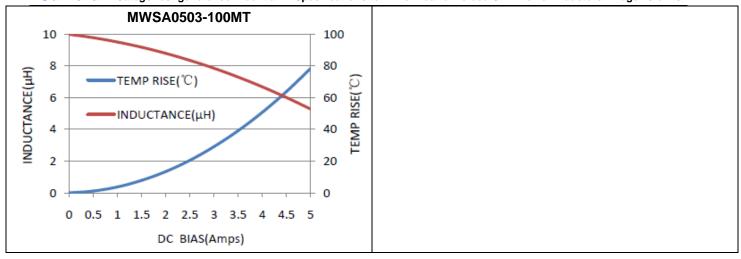


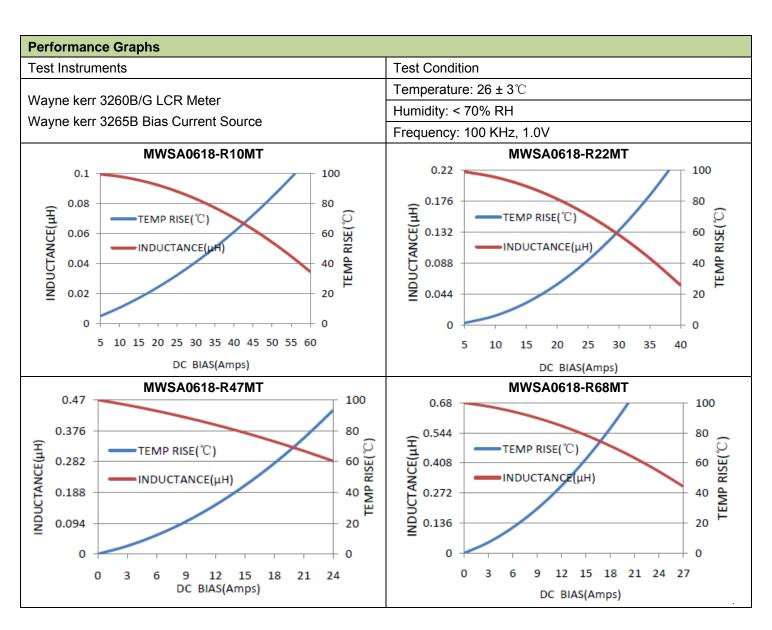
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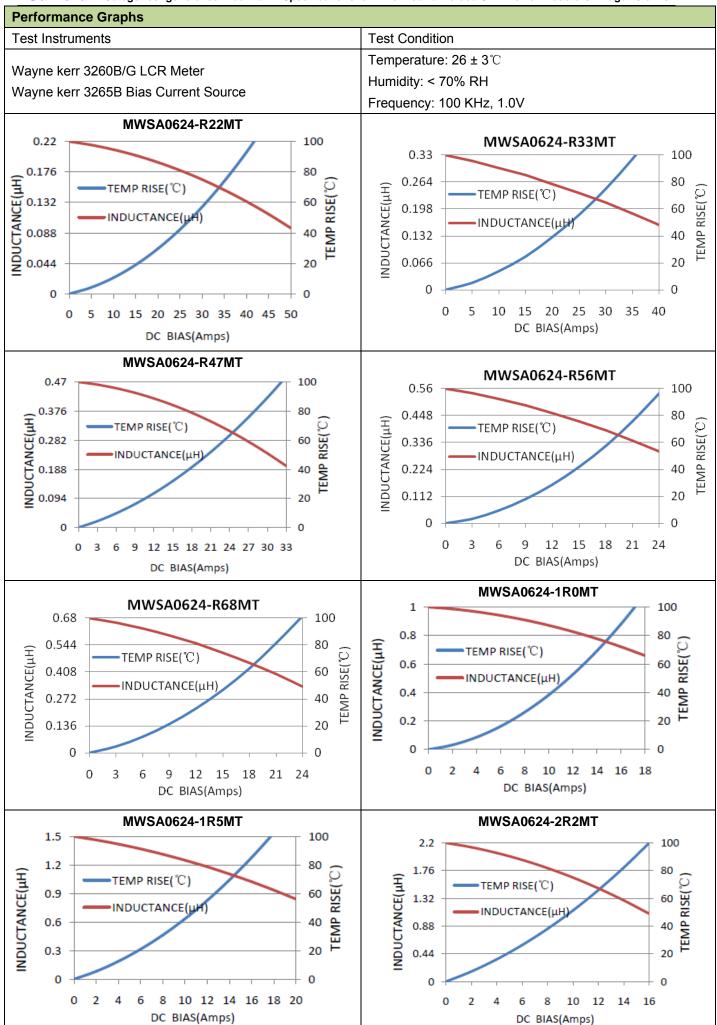
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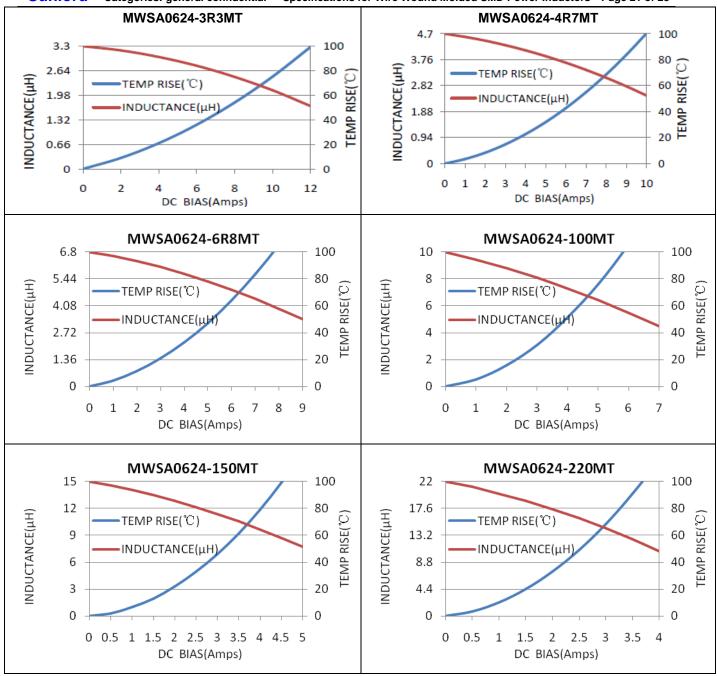
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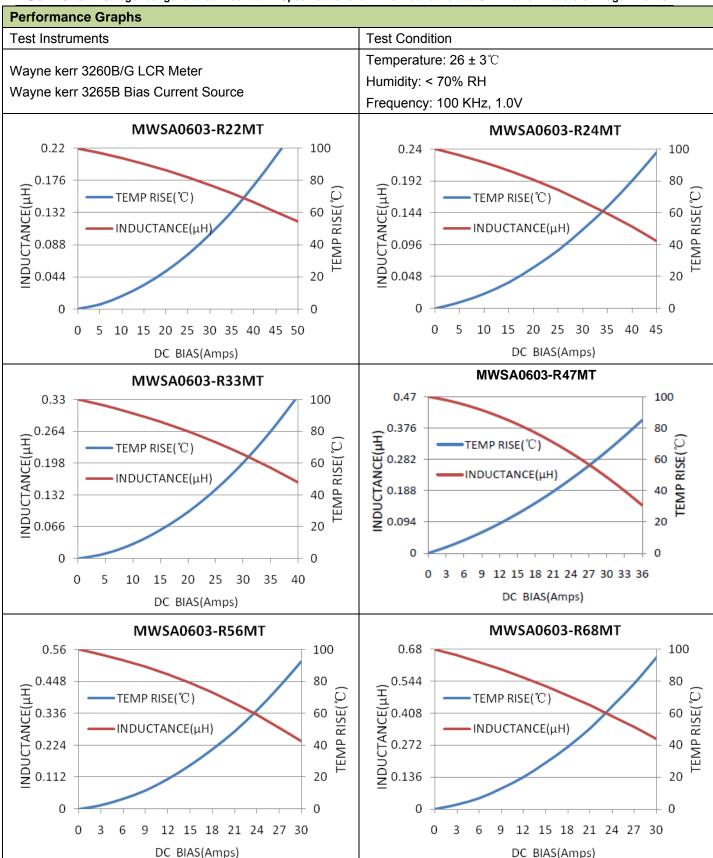
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DC BIAS(Amps)

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DC BIAS(Amps)

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